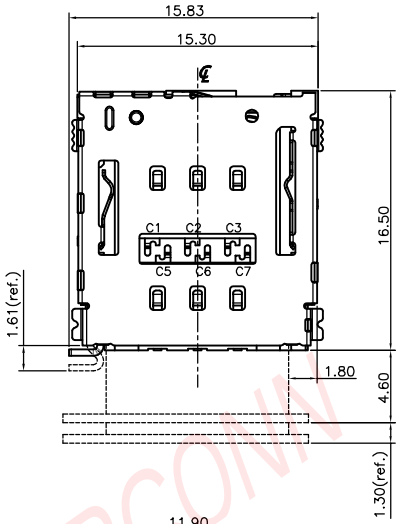
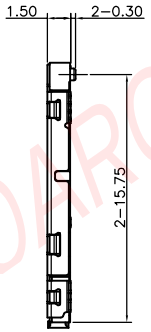
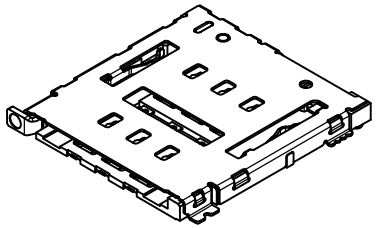
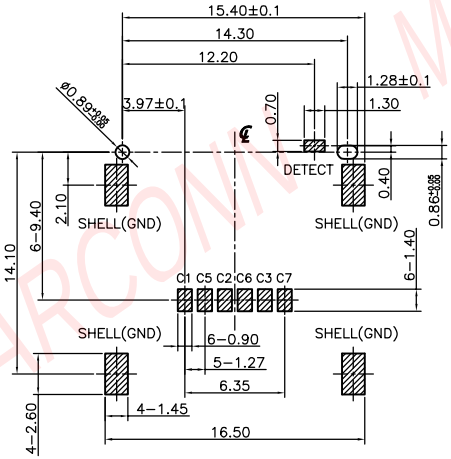
All materials, plating and process meet HF requirements.



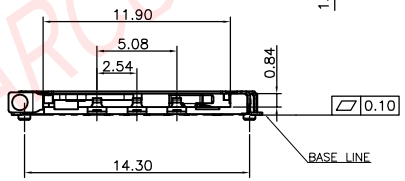


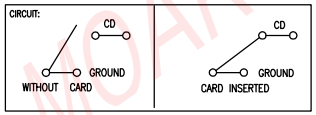






RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05 (TOP VIEW)





NOTES:

1 MATERIAL:
- 1-1 HOUSING: THERMOPLASTIC, UL94V-0; COLOR: BLACK
- 1-2 SHIELDED: STAINLESS STEEL
- 1-3 CONTACT: COPPER ALLOY
- 1-4 SWITCH PIN: COPPER ALLOY

2 FINISH:
- 2-1 CONTACT: Au PLATING ON CONTACT AREA 50u" MIN. NICKEL UNDERPLATING OVER ALL 1u"MIN. Au PLANTING ON SOLD AREA,
- 2-2 SHIELDED: 1u" MIN. Au PLATING ON SECURED AREA

3 PRODUCT SPECIFICATIONS:
- 3-1 VOLTAGE RATING: 50V
- 3-2 WITHSTANDING VOLTAGE: AC250V R.M.S
- 3-3 CURRENT RATING: 0.5A
- 3-4 INSULATION RESISTANCE: 1000 MEGAOHMS MIN. AT DC 250V
- 3-5 CONTACT RESISTANCE: 100 MILLIOHMS MAX.
- 3-6 OPERATION TEMPERATURE: -20° TO +85°

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	----	NEW RELEASE	Alexander	2024.11.04

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DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.25
X.XXX: ±	0.10
ANGULAR: ±	2°

PRODUCT NAME : NANO SIM H1.50带侦测PIN左推杆	DRAWING: Alexander	DATE: 2024.11.04	
PRODUCT NO. : NS150-T1151-30	CHECK: /	DATE: /	
DRAWING NO. : D-NS150-T1151-30	APPROVED: Aaron	DATE: 2024.11.23	
	SCALE: 1:1	DWG ID: C D	REV.: X0
			PAGE: 1 OF 1

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